

Technical Specification for Stand-Alone Router SAR-1300 New Generation



1. Technical Data of the Machine

1.1. Machine Dimensions

- Width + monitor 1,324 mm + approx. 408 mm
- Depth + shuttle 1,386 mm + shuttle 712 mm (total depth 2098)
- Height 1,930 mm
- Operator height approx. 930 mm
- Weight approx. 1,600 kg

1.2. Supply

- Voltage 400 V / 50 Hz / 16 A
- Compressed air 0.6mPa (6bar), oil-free, filtered and dry
- Consumption approx. 100 l/min with 1 milling spindle
- Ambient temperature + 18°C to + 40°C
- Relative humidity 10% to 80%

RC Connection not possible (consultation)

1.3. Noise level

- Measured at a distance of 1.2 m around the machine without silencing <= 72 db (A)
with silencing <= 68 db (A)

1.4. Speed

- X,Y standard linear motor axes 1,000 mm/s
- X,Y high-speed linear motor axes 2,000 mm/s
- Z-axis linear motor axis 1,000 mm/s

1.5. Levels of Accuracy

- Repeat accuracy ± 0.02 mm
- Position accuracy ± 0.02 mm
- Milling accuracy ± 0.15 mm (without camera)
± 0.10 mm (with camera)

1.6. Working Range and PCB Characteristics standard shuttle axis

- Max. milling area 430 mm x 350 mm
- Max. multi panel size 430 mm x 350 mm
- PCB thickness 0.5 mm to 3.2 mm
- Max. component height spindle 0.4 KW Top side: 10 mm
- Max. component height spindle 0.5 KW Top side: 20 mm
- Max. disc milling bit component height Top side: 12mm
- Maximum component height bottom side: 35 mm (standard shuttle)
- Standard shuttle Maximum panel thickness on base plate on machine: 70 mm
- Locating holes within the individual PCB
- Optimal min. 2 holes/PCB with at least \varnothing 1mm
- Max. distortion of printed circuit board 1% of length/width
- Printed circuit board materials CEM, FR4, IMS(AL), CU

1.7. Shuttle system standard shuttle axis

- Change cycle with double shuttle < 2 sec
- Format per workpiece carrier 1300 555 mm x 380 mm x 12 mm
- Product change time/tooling time < 4 min

1.8. Working range and PCB characteristics high shuttle axis

- Max. milling area 430 mm x 380 mm
- Max. multi panel size 430 mm x 380 mm
- PCB thickness 0.5 mm to 3.2 mm
- Max. component height spindle 0.4 KW Top side: 10 mm
- Max. component height spindle 0.5 KW Top side: 20 mm
- Max. disc milling bit component height Top side: 12mm
- Maximum component height bottom side: 105 mm (high shuttle)
- High shuttle maximum panel thickness on base plate on machine: 152 mm
- Locating holes within the individual PCB
- Optimal min. 2 holes/PCB with at least \varnothing 1mm
- Max. distortion of printed circuit board 1% of length/width
- Printed circuit board materials CEM, FR4, IMS(AL), CU

The present technical specification are subject to modification without prior written notice